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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Not For New Designs
Number of LABs/CLBs	2625
Number of Logic Elements/Cells	21000
Total RAM Bits	282624
Number of I/O	131
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-20e-5qn208c

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

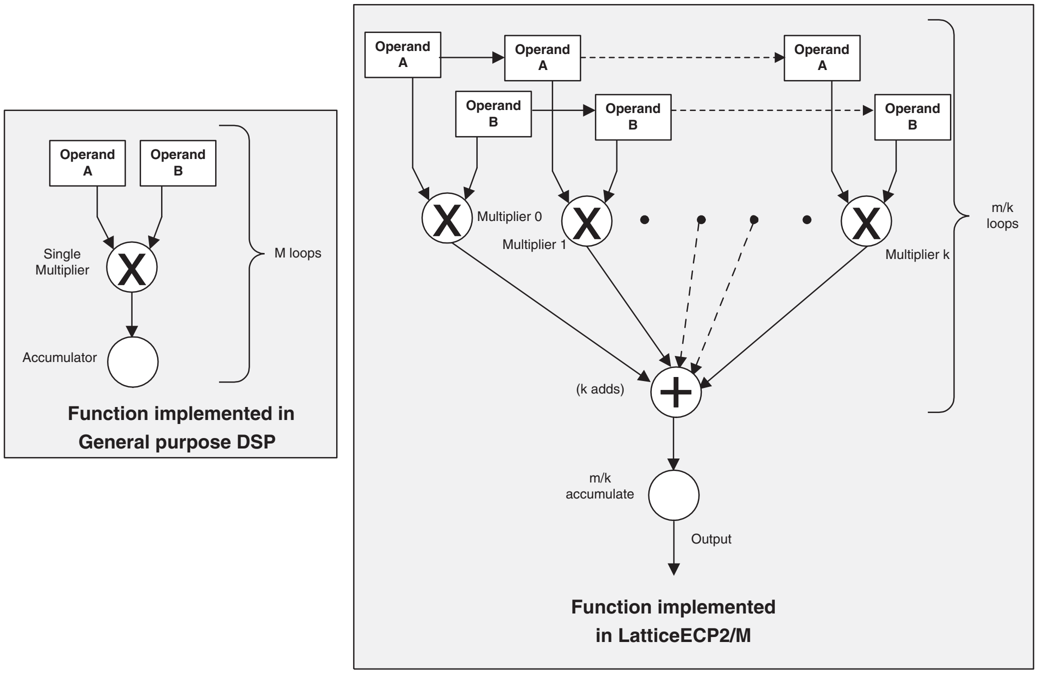
sysDSP™ Block

The LatticeECP2/M family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP2/M, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-22 compares the fully serial and the mixed parallel and serial implementations.

Figure 2-22. Comparison of General DSP and LatticeECP2/M Approaches



sysDSP Block Capabilities

The sysDSP block in the LatticeECP2/M family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP2/M family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block. In the LatticeECP2/M family the DSP elements can be concatenated.

The resources in each sysDSP block can be configured to support the following elements:

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In- System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, LatticeECP2/M sysCONFIG Usage Guide for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. **Decryption Support**
   LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. **TransFR (Transparent Field Reconfiguration)**
   TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology, for details.

3. **Dual Boot Image Support**
   Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

LatticeECP2 Initialization Supply Current[1, 2, 3, 4]

Over Recommended Operating Conditions

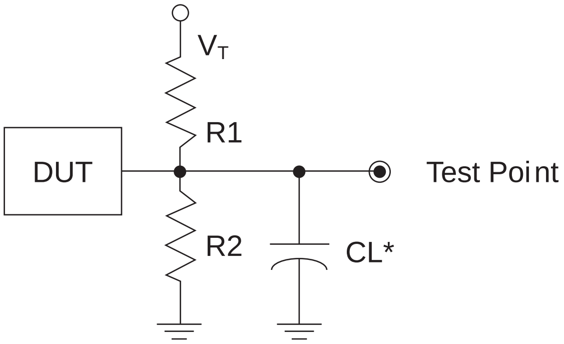
Symbol	Parameter	Device	Typ.[5, 6, 7]	Units
I_{CC}	Core Power Supply Current	ECP2-6	34	mA
		ECP2-12	54	mA
		ECP2-20	82	mA
		ECP2-35	135	mA
		ECP2-50	187	mA
		ECP2-70	267	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2-6	30	mA
		ECP2-12	30	mA
		ECP2-20	30	mA
		ECP2-35	30	mA
		ECP2-50	30	mA
		ECP2-70	30	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	ECP2-35, -50, -70 Only	0.5	mA
I_{CCSPLL}	SPLL Power Supply Current (per SPLL)	ECP2-35, -50, -70 Only	0.5	mA
I_{CCIO}	Bank Power Supply Current (per Bank)	All Devices	3	mA
I_{CCJ}	VCCJ Power Supply Current	All Devices	4	mA

1. Until DONE signal is active.
2. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. A specific configuration pattern is used that scales with the size of the device; consists of 75% PFU utilization, 50% EBR, and 25% I/O configuration.
7. Values shown in this column are the typical average DC current during configuration. Use the Power Calculator tool to find the peak startup current.

Switching Test Conditions

Figure 3-22 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-19.

Figure 3-22. Output Test Load, LVTTL and LVCMOS Standards



*CL Includes Test Fixture and Probe Capacitance

Table 3-19. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	R_2	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	∞	0pF	LVCMOS 3.3 = 1.5V	—
				LVCMOS 2.5 = $V_{CCIO}/2$	—
				LVCMOS 1.8 = $V_{CCIO}/2$	—
				LVCMOS 1.5 = $V_{CCIO}/2$	—
				LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	∞	1MΩ		$V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> L)	1MΩ	∞		$V_{CCIO}/2$	V_{CCIO}
LVCMOS 2.5 I/O (H -> Z)	∞	100		V_{OH} - 0.10	—
LVCMOS 2.5 I/O (L -> Z)	100	∞		V_{OL} + 0.10	V_{CCIO}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
[LOC]_SQ_VCCIBm	—	Input buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_VCCOBm	—	Output buffer power supply, channel m (1.2V/1.5V). This pin should be left floating if the channel is unused.
[LOC]_SQ_HDOUTNm	O	High-speed output, negative channel m
[LOC]_SQ_HDOUTPm	O	High-speed output, positive channel m
[LOC]_SQ_HDINNm	I	High-speed input, negative channel m
[LOC]_SQ_HDINPm	I	High-speed input, positive channel m
[LOC]_SQ_VCCTXm[4]	—	Transmitter power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.
[LOC]_SQ_VCCRXm[4]	—	Receiver power supply, channel m (1.2V). This pin must be tied to 1.2V even if the channel is unused.

1. These signals are relevant for LatticeECP2M family.
2. m defines the associated channel in the Quad.
3. These signals are defined in Quads [LOC] indicates the corner SERDES Quad is located: ULC (upper left), URC (upper right), LLC (lower left), LRC (lower right).
4. When placing switching I/Os around these critical pins that are designed to supply the device with the proper reference or supply voltage, care must be given. For more information, refer to TN1159, LatticeECP2/M Pin Assignment Recommendations.
5. There may be SPLLs that do not have dedicated I/Os.

LatticeECP2 Pin Information Summary, LFE2-20 and LFE2-35 (Cont.)

Pin Type		LFE2-20				LFE2-35	
		208 PQFP	256 fpBGA	484 fpBGA	672 fpBGA	484 fpBGA	672 fpBGA
Available DDR-Interfaces per I/O Bank[1]	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	1	2	2	2	3
	Bank3	0	0	0	2	0	2
	Bank4	0	2	3	3	3	3
	Bank5	0	1	3	4	3	4
	Bank6	0	1	2	3	1	3
	Bank7	0	1	2	2	2	3
	Bank8	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	0	0	0	0	0
	Bank3	0	0	0	0	0	0
	Bank4	19	32	46	50	46	54
	Bank5	18	17	46	68	46	68
	Bank6	0	0	0	0	0	0
	Bank7	0	0	0	0	0	0
	Bank8	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
GND	GND	GNDIO5	-		
R4	R4	PB33A	5	BDQS33	T
L6	L6	PB34A	5	BDQ33	T
T4	T4	PB33B	5	BDQ33	C
L7	L7	PB34B	5	BDQ33	C
N7	N7	PB35A	5	PCLKT5_0/BDQ33	T
VCCIO	VCCIO	VCCIO5	5		
M8	M8	PB35B	5	PCLKC5_0/BDQ33	C
GND	GND	GNDIO5	-		
P7	P7	PB40A	4	PCLKT4_0/BDQ42	T
R8	R8	PB40B	4	PCLKC4_0/BDQ42	C
VCCIO	VCCIO	VCCIO4	4		
T5	T5	PB41A	4	BDQ42	T
T6	T6	PB41B	4	BDQ42	C
T8	T8	PB42A	4	BDQS42	T
GND	GND	GNDIO4	-		
R7	R7	PB43A	4	BDQ42	T
T9	T9	PB42B	4	BDQ42	C
T7	T7	PB43B	4	BDQ42	C
L8	L8	PB44A	4	BDQ42	T
VCCIO	VCCIO	VCCIO4	4		
P8	P8	PB45A	4	BDQ42	T
L9	L9	PB44B	4	BDQ42	C
N8	N8	PB45B	4	BDQ42	C
R9	R9	PB46A	4	BDQ42	T
GND	GND	GNDIO4	-		
R10	R10	PB46B	4	BDQ42	C
-	VCC	VCCIO	4		
-	GND	GNDIO4	4		
N9	N9	PB56A	4	BDQ60	T
T10	T10	PB57A	4	BDQ60	T
M9	M9	PB56B	4	BDQ60	C
R11	R11	PB57B	4	BDQ60	C
P10	P10	PB58A	4	BDQ60	T
N11	N11	PB59A	4	BDQ60	T
VCCIO	VCCIO	VCCIO4	4		
N10	N10	PB58B	4	BDQ60	C
P11	P11	PB59B	4	BDQ60	C
T11	T11	PB60A	4	BDQS60	T
GND	GND	GNDIO4	-		
M11	M11	PB61A	4	BDQ60	T
T12	T12	PB60B	4	BDQ60	C

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AB7	PB13B	5	BDQ15	C	PB22B	5	BDQ24	C
Y8	PB16A	5	BDQ15	T	PB25A	5	BDQ24	T
GNDIO	GNDIO5	-			GNDIO	-		
W9	PB15A	5	BDQS15	T	PB24A	5	BDQS24	T
AA8	PB16B	5	BDQ15	C	PB25B	5	BDQ24	C
V9	PB15B	5	BDQ15	C	PB24B	5	BDQ24	C
AB8	PB18A	5	BDQ15	T	PB27A	5	BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		
W10	PB17A	5	BDQ15	T	PB26A	5	BDQ24	T
AA9	PB18B	5	BDQ15	C	PB27B	5	BDQ24	C
V10	PB17B	5	BDQ15	C	PB26B	5	BDQ24	C
GNDIO	GNDIO5	-			GNDIO	-		
Y10	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AB9	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
AA10	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AB10	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
AB11	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
U10	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AA11	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
U11	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
GNDIO	GNDIO5	-			GNDIO5	-		
AB12	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
Y11	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
AA12	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
W11	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AB13	PB26A	5	PCLKT5_0/BDQ24	T	PB35A	5	PCLKT5_0/BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AB14	PB26B	5	PCLKC5_0/BDQ24	C	PB35B	5	PCLKC5_0/BDQ33	C
GNDIO	GNDIO5	-			GNDIO5	-		
Y12	PB32A	4	BDQ33	T	PB41A	4	BDQ42	T
W12	PB32B	4	BDQ33	C	PB41B	4	BDQ42	C
VCCIO	VCCIO4	4			VCCIO4	4		
U12	PB31A	4	PCLKT4_0/BDQ33	T	PB40A	4	PCLKT4_0/BDQ42	T
V12	PB31B	4	PCLKC4_0/BDQ33	C	PB40B	4	PCLKC4_0/BDQ42	C
U13	PB34A	4	BDQ33	T	PB43A	4	BDQ42	T
GNDIO	GNDIO4	-			GNDIO4	-		
AA13	PB33A	4	BDQS33	T	PB42A	4	BDQS42	T
U14	PB34B	4	BDQ33	C	PB43B	4	BDQ42	C
Y13	PB33B	4	BDQ33	C	PB42B	4	BDQ42	C
AB16	PB36A	4	BDQ33	T	PB45A	4	BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
AB15	PB35A	4	BDQ33	T	PB44A	4	BDQ42	T
AB17	PB36B	4	BDQ33	C	PB45B	4	BDQ42	C

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
E4	PL2A	7	VREF2_7/LDQ6	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
E5	PL2B	7	VREF1_7/LDQ6	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO7	-			GNDIO7	-		
GNDIO	GNDIO7	-			VCCIO	7		
E3	PL10A	7	LDQ14	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*
F3	PL10B	7	LDQ14	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*
F4	PL11A	7	LDQ14	T	PL13A	7	LDQ16	T
F5	PL11B	7	LDQ14	C	PL13B	7	LDQ16	C
E2	PL12A	7	LDQ14	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO	7		
E1	PL12B	7	LDQ14	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*
G6	PL13A	7	LDQ14	T	PL15A	7	LDQ16	T
G7	PL13B	7	LDQ14	C	PL15B	7	LDQ16	C
H4	PL14A	7	LDQS14	T (LVDS)*	PL16A	7	LDQS16	T (LVDS)*
GNDIO	GNDIO7	-			GNDIO7	-		
H5	PL14B	7	LDQ14	C (LVDS)*	PL16B	7	LDQ16	C (LVDS)*
F1	PL15A	7	LDQ14	T	PL17A	7	LDQ16	T
F2	PL15B	7	LDQ14	C	PL17B	7	LDQ16	C
VCCIO	VCCIO7	7			VCCIO	7		
G3	PL16A	7	LDQ14	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*
G4	PL16B	7	LDQ14	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*
G1	PL17A	7	LDQ14	T	PL19A	7	LDQ16	T
G2	PL17B	7	LDQ14	C	PL19B	7	LDQ16	C
GNDIO	GNDIO7	-			GNDIO7	-		
-	-	-			VCCIO	7		
H6	NC	-			PL25A	7	LUM0_SPLLT_IN_A/LDQ24	T
-	-	-			VCCIO	7		
J6	NC	-			PL25B	7	LUM0_SPLLC_IN_A/LDQ24	C
H3	NC	-			PL26A	7	LUM0_SPLLT_FB_A/LDQ24	T
H2	NC	-			PL26B	7	LUM0_SPLLC_FB_A/LDQ24	C
-	-	-			GNDIO7	-		
-	-	-			VCCIO	7		
H1	PL18A	7	LDQ22		PL37A	7	LDQ41	
J4	PL19A	7	LDQ22	T	PL38A	7	LDQ41	T
J5	PL19B	7	LDQ22	C	PL38B	7	LDQ41	C
VCCIO	VCCIO7	7			VCCIO	7		
J2	PL20A	7	LDQ22	T (LVDS)*	PL39A	7	LDQ41	T (LVDS)*
J1	PL20B	7	LDQ22	C (LVDS)*	PL39B	7	LDQ41	C (LVDS)*
L6	PL21A	7	LDQ22	T	PL40A	7	LDQ41	T
L5	PL21B	7	LDQ22	C	PL40B	7	LDQ41	C
GNDIO	GNDIO7	-			GNDIO7	-		
K3	PL22A	7	LDQS22	T (LVDS)*	PL41A	7	LDQS41	T (LVDS)*
K4	PL22B	7	LDQ22	C (LVDS)*	PL41B	7	LDQ41	C (LVDS)*
K2	PL23A	7	LDQ22	T	PL42A	7	LDQ41	T
VCCIO	VCCIO7	7			VCCIO	7		

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G17	PR13B	2	RDQ14	C	PR15B	2	RDQ16	C
F19	PR13A	2	RDQ14	T	PR15A	2	RDQ16	T
E20	PR12B	2	RDQ14	C (LVDS)*	PR14B	2	RDQ16	C (LVDS)*
D20	PR12A	2	RDQ14	T (LVDS)*	PR14A	2	RDQ16	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO	2		
F18	PR11B	2	RDQ14	C	PR13B	2	RDQ16	C
F16	PR11A	2	RDQ14	T	PR13A	2	RDQ16	T
C21	PR10B	2	RDQ14	C (LVDS)*	PR12B	2	RDQ16	C (LVDS)*
C22	PR10A	2	RDQ14	T (LVDS)*	PR12A	2	RDQ16	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO	2		
GNDIO	GNDIO2	-			GNDIO2	-		
D19	PR2B	2	VREF2_2/RDQ6	C (LVDS)*	PR2B	2	VREF2_2	C (LVDS)*
E19	PR2A	2	VREF1_2/RDQ6	T (LVDS)*	PR2A	2	VREF1_2	T (LVDS)*
B21	PT73B	1	VREF2_1	C	PT82B	1	VREF2_1	C
GNDIO	GNDIO1	-			GNDIO1	-		
B22	PT73A	1	VREF1_1	T	PT82A	1	VREF1_1	T
C20	PT72B	1		C	PT81B	1		C
C19	PT72A	1		T	PT81A	1		T
D18	PT71B	1		C	PT80B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
E18	PT71A	1		T	PT80A	1		T
B20	PT70B	1		C	PT79B	1		C
A19	PT70A	1		T	PT79A	1		T
D17	PT69B	1		C	PT78B	1		C
C18	PT69A	1		T	PT78A	1		T
A21	PT68B	1		C	PT77B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
A20	PT68A	1		T	PT77A	1		T
A18	PT67B	1		C	PT76B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
B18	PT67A	1		T	PT76A	1		T
G16	PT66B	1		C	PT75B	1		C
G15	PT66A	1		T	PT75A	1		T
D16	PT65B	1		C	PT74B	1		C
E16	PT65A	1		T	PT74A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO	1		
C17	PT55B	1		C	PT64B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
C16	PT55A	1		T	PT64A	1		T
B17	PT54B	1		C	PT63B	1		C
B16	PT54A	1		T	PT63A	1		T
A17	PT53B	1		C	PT62B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
A16	PT53A	1		T	PT62A	1		T
C15	PT52B	1		C	PT61B	1		C

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C8	PT29B	0		C	PT38B	0		C
D8	PT29A	0		T	PT38A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
D10	PT27B	0		C	PT36B	0		C
E10	PT27A	0		T	PT36A	0		T
C7	PT26B	0		C	PT35B	0		C
C6	PT26A	0		T	PT35A	0		T
VCCIO	VCCIO0	0			VCCIO	0		
B6	PT25B	0		C	PT34B	0		C
B5	PT25A	0		T	PT34A	0		T
F10	PT24B	0		C	PT33B	0		C
D9	PT24A	0		T	PT33A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
F9	PT23B	0		C	PT32B	0		C
E9	PT23A	0		T	PT32A	0		T
A5	PT22B	0		C	PT31B	0		C
A4	PT22A	0		T	PT31A	0		T
VCCIO	VCCIO0	0			VCCIO	0		
A3	PT21B	0		C	PT30B	0		C
A2	PT21A	0		T	PT30A	0		T
G8	PT20B	0		C	PT29B	0		C
E8	PT20A	0		T	PT29A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
VCCIO	VCCIO0	0			VCCIO	0		
C3	PT10B	0		C	PT10B	0		C
B3	PT10A	0		T	PT10A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
F8	PT9B	0		C	PT9B	0		C
D7	PT9A	0		T	PT9A	0		T
E7	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO	0		
F7	PT8A	0		T	PT8A	0		T
D5	PT7B	0		C	PT7B	0		C
D6	PT7A	0		T	PT7A	0		T
D4	PT6B	0		C	PT6B	0		C
C4	PT6A	0		T	PT6A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
B2	PT5B	0		C	PT5B	0		C
B1	PT5A	0		T	PT5A	0		T
J7	PT4B	0		C	PT4B	0		C
VCCIO	VCCIO0	0			VCCIO	0		
H7	PT4A	0		T	PT4A	0		T
D3	PT3B	0		C	PT3B	0		C
C2	PT3A	0		T	PT3A	0		T
D1	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
C1	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L2	PL24B	7	LDQ24	C (LVDS)*	PL37B	7	LDQ37	C (LVDS)*
L1	PL25A	7	LUM0_SPLLT_IN_A/LDQ24	T	PL38A	7	LUM0_SPLLT_IN_A/LDQ37	T
VCCIO	VCCIO7	7			VCCIO7	7		
M2	PL25B	7	LUM0_SPLLC_IN_A/LDQ24	C	PL38B	7	LUM0_SPLLC_IN_A/LDQ37	C
M1	PL26A	7	LUM0_SPLLT_FB_A/LDQ24	T	PL39A	7	LUM0_SPLLT_FB_A/LDQ37	T
N2	PL26B	7	LUM0_SPLLC_FB_A/LDQ24	C	PL39B	7	LUM0_SPLLC_FB_A/LDQ37	C
GND	GNDIO7	-			GNDIO7	-		
M8	VCCPLL	7			NC	-		
VCCIO	VCCIO7	7			VCCIO7	7		
GND	GNDIO7	-			GNDIO7	-		
N1	PL37A	7	LDQ41		PL50A	7	LDQ54	
L8	PL38A	7	LDQ41	T	PL51A	7	LDQ54	T
K8	PL38B	7	LDQ41	C	PL51B	7	LDQ54	C
VCCIO	VCCIO7	7			VCCIO7	7		
L6	PL39A	7	LDQ41	T (LVDS)*	PL52A	7	LDQ54	T (LVDS)*
K5	PL39B	7	LDQ41	C (LVDS)*	PL52B	7	LDQ54	C (LVDS)*
L7	PL40A	7	LDQ41	T	PL53A	7	LDQ54	T
L5	PL40B	7	LDQ41	C	PL53B	7	LDQ54	C
GND	GNDIO7	-			GNDIO7	-		
P1	PL41A	7	LDQS41	T (LVDS)*	PL54A	7	LDQS54	T (LVDS)*
P2	PL41B	7	LDQ41	C (LVDS)*	PL54B	7	LDQ54	C (LVDS)*
M6	PL42A	7	LDQ41	T	PL55A	7	LDQ54	T
VCCIO	VCCIO7	7			VCCIO7	7		
N8	PL42B	7	LDQ41	C	PL55B	7	LDQ54	C
R1	PL43A	7	LDQ41	T (LVDS)*	PL56A	7	LDQ54	T (LVDS)*
R2	PL43B	7	LDQ41	C (LVDS)*	PL56B	7	LDQ54	C (LVDS)*
M7	PL44A	7	PCLKT7_0/LDQ41	T	PL57A	7	PCLKT7_0/LDQ54	T
GND	GNDIO7	-			GNDIO7	-		
N9	PL44B	7	PCLKC7_0/LDQ41	C	PL57B	7	PCLKC7_0/LDQ54	C
M4	PL46A	6	PCLKT6_0/LDQ50	T (LVDS)*	PL59A	6	PCLKT6_0/LDQ63	T (LVDS)*
M5	PL46B	6	PCLKC6_0/LDQ50	C (LVDS)*	PL59B	6	PCLKC6_0/LDQ63	C (LVDS)*
N7	PL47A	6	VREF2_6/LDQ50	T	PL60A	6	VREF2_6/LDQ63	T
P9	PL47B	6	VREF1_6/LDQ50	C	PL60B	6	VREF1_6/LDQ63	C
N3	PL48A	6	LDQ50	T (LVDS)*	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
N4	PL48B	6	LDQ50	C (LVDS)*	PL61B	6	LDQ63	C (LVDS)*
N5	PL49A	6	LDQ50	T	PL62A	6	LDQ63	T
P7	PL49B	6	LDQ50	C	PL62B	6	LDQ63	C
T1	PL50A	6	LDQS50	T (LVDS)*	PL63A	6	LDQS63	T (LVDS)*
GND	GNDIO6	-			GNDIO6	-		
T2	PL50B	6	LDQ50	C (LVDS)*	PL63B	6	LDQ63	C (LVDS)*
P8	PL51A	6	LDQ50	T	PL64A	6	LDQ63	T
P6	PL51B	6	LDQ50	C	PL64B	6	LDQ63	C
VCCIO	VCCIO6	6			VCCIO6	6		
P5	PL52A	6	LDQ50	T (LVDS)*	PL65A	6	LDQ63	T (LVDS)*
P4	PL52B	6	LDQ50	C (LVDS)*	PL65B	6	LDQ63	C (LVDS)*

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AH12	PB45A	5	BDQ42	T
AF14	PB45B	5	BDQ42	C
AJ13	PB46A	5	BDQ42	T
GND	GNDIO5	-		
AK13	PB46B	5	BDQ42	C
AB15	PB47A	5	BDQ51	T
AD15	PB47B	5	BDQ51	C
AE15	PB48A	5	BDQ51	T
AF15	PB48B	5	BDQ51	C
AG15	PB49A	5	BDQ51	T
AG14	PB49B	5	BDQ51	C
VCCIO	VCCIO5	5		
AH15	PB50A	5	BDQ51	T
AH14	PB50B	5	BDQ51	C
GND	GNDIO5	-		
AJ14	PB51A	5	BDQS51	T
AK14	PB51B	5	BDQ51	C
AD16	PB52A	5	BDQ51	T
AF16	PB52B	5	BDQ51	C
AJ15	PB53A	5	PCLKT5_0/BDQ51	T
AK15	PB53B	5	PCLKC5_0/BDQ51	C
VCCIO	VCCIO5	5		
GND	GNDIO5	-		
AE16	PB58A	4	PCLKT4_0/BDQ60	T
VCCIO	VCCIO4	4		
AC15	PB58B	4	PCLKC4_0/BDQ60	C
AJ16	PB59A	4	BDQ60	T
AK16	PB59B	4	BDQ60	C
AC16	PB60A	4	BDQS60	T
GND	GNDIO4	-		
AB16	PB60B	4	BDQ60	C
AH17	PB61A	4	BDQ60	T
AG17	PB61B	4	BDQ60	C
AF17	PB62A	4	BDQ60	T
VCCIO	VCCIO4	4		
AD17	PB62B	4	BDQ60	C
AE17	PB63A	4	BDQ60	T
AC17	PB63B	4	BDQ60	C
AJ17	PB64A	4	BDQ60	T
GND	GNDIO4	-		
AK17	PB64B	4	BDQ60	C
AK18	PB65A	4	BDQ69	T
AJ18	PB65B	4	BDQ69	C

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
A2	PL2A	7	LDQ6	T (LVDS)*	PL2A	7	LDQ6	T (LVDS)*
B2	PL2B	7	LDQ6	C (LVDS)*	PL2B	7	LDQ6	C(LVDS)*
D3	PL3A	7	LDQ6	T	PL3A	7	LDQ6	T
C2	PL3B	7	LDQ6	C	PL3B	7	LDQ6	C
E4	PL4A	7	LDQ6	T (LVDS)*	PL4A	7	LDQ6	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO7	7		
E5	PL4B	7	LDQ6	C (LVDS)*	PL4B	7	LDQ6	C(LVDS)*
B1	PL5A	7	LDQ6	T	PL5A	7	LDQ6	T
C1	PL5B	7	LDQ6	C	PL5B	7	LDQ6	C
D2	PL6A	7	LDQS6	T (LVDS)*	PL6A	7	LDQS6	T (LVDS)*
GNDIO	GNDIO7	-			GNDIO7	-		
D1	PL6B	7	LDQ6	C (LVDS)*	PL6B	7	LDQ6	C(LVDS)*
E1	PL7A	7	LDQ6	T	PL7A	7	LDQ6	T
F1	PL7B	7	LDQ6	C	PL7B	7	LDQ6	C
VCCIO	VCCIO7	7			VCCIO7	7		
F3	PL8A	7	LDQ6	T (LVDS)*	PL8A	7	LDQ6	T (LVDS)*
F2	PL8B	7	LDQ6	C (LVDS)*	PL8B	7	LDQ6	C(LVDS)*
F6	PL9A	7	VREF2_7/LDQ6	T	PL9A	7	VREF2_7/LDQ6	T
F5	PL9B	7	VREF1_7/LDQ6	C	PL9B	7	VREF1_7/LDQ6	C
GNDIO	GNDIO7	-			GNDIO7	-		
G4	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*
G3	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C(LVDS)*
G1	PL12A	7	LUM0_SPLLT_FB_A	T	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T
G2	PL12B	7	LUM0_SPLLC_FB_A	C	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C
H1	PL13A	7		T (LVDS)*	PL13A	7	LDQ15	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO7	7		
J1	PL13B	7		C (LVDS)*	PL13B	7	LDQ15	C(LVDS)*
H2	PL14A	7		T	PL14A	7	LDQ15	T
H3	PL14B	7		C	PL14B	7	LDQ15	C
GNDIO	GNDIO7	-			GNDIO7	-		
VCCIO	VCCIO7	7			VCCIO7	7		
G6	PL24A	7	LDQ22	T (LVDS)*	PL34A	7	LDQ32	T (LVDS)*
H6	PL24B	7	LDQ22	C (LVDS)*	PL34B	7	LDQ32	C(LVDS)*
J2	PL25A	7	PCLKT7_0/LDQ22	T	PL35A	7	PCLKT7_0/LDQ32	T
GNDIO	GNDIO7	-			GNDIO7	-		
K1	PL25B	7	PCLKC7_0/LDQ22	C	PL35B	7	PCLKC7_0/LDQ32	C
H4	PL27A	6	PCLKT6_0	T (LVDS)*	PL37A	6	PCLKT6_0	T (LVDS)*
H5	PL27B	6	PCLKC6_0	C (LVDS)*	PL37B	6	PCLKC6_0	C(LVDS)*
J4	PL28A	6	VREF2_6	T	PL38A	6	VREF2_6	T
K4	PL28B	6	VREF1_6	C	PL38B	6	VREF1_6	C
VCCIO	VCCIO6	6			VCCIO6	6		
J6	PL31A	6	LLM1_SPLLT_IN_A	T (LVDS)*	PL41A	6	LLM2_SPLLT_IN_A	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
J5	PL31B	6	LLM1_SPLLC_IN_A	C (LVDS)*	PL41B	6	LLM2_SPLLC_IN_A	C(LVDS)*
K3	PL32A	6	LLM1_SPLLT_FB_A	T	PL42A	6	LLM2_SPLLT_FB_A	T
K2	PL32B	6	LLM1_SPLLC_FB_A	C	PL42B	6	LLM2_SPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
T17	PR51A	8	D2***	T	PR66A	8	D2***	T
T22	PR50B	8	D3***	C	PR65B	8	D3***	C
GNDIO	GNDIO8	-			GNDIO8	-		
R22	PR50A	8	D4***	T	PR65A	8	D4***	T
T15	PR49B	8	D5***	C	PR64B	8	D5***	C
R17	PR49A	8	D6***	T	PR64A	8	D6***	T
T20	PR48B	8	D7/SPID0***	C	PR63B	8	D7/SPID0***	C
VCCIO	VCCIO8	8			VCCIO8	8		
T21	PR48A	8	DI/CSSPI0N***	T	PR63A	8	DI/CSSPI0N***	T
R21	PR47B	8	DOUT/CSON/CSSPI1N***	C	PR62B	8	DOUT/CSON/CSSPI1N***	C
R20	PR47A	8	BUSY/SISPI***	T	PR62A	8	BUSY/SISPI***	T
R16	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
R18	PR45B	3	RLM0_GDLLC_FB_A	C	PR60B	3	RLM0_GDLLC_FB_A/RDQ57	C
GNDIO	GNDIO3	-			GNDIO3	-		
R19	PR45A	3	RLM0_GDLLT_FB_A	T	PR60A	3	RLM0_GDLLT_FB_A/RDQ57	T
P22	PR44B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR59B	3	RLM0_GDLLC_IN_A**/RDQ57	C (LVDS)*
P21	PR44A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR59A	3	RLM0_GDLLT_IN_A**/RDQ57	T (LVDS)*
P16	PR43B	3	RLM0_GPLLC_IN_A**	C	PR58B	3	RLM0_GPLLC_IN_A**/RDQ57	C
VCCIO	VCCIO3	3			VCCIO3	3		
P17	PR43A	3	RLM0_GPLLT_IN_A**	T	PR58A	3	RLM0_GPLLT_IN_A**/RDQ57	T
P20	PR42B	3	RLM0_GPLLC_FB_A	C (LVDS)*	PR57B	3	RLM0_GPLLC_FB_A/RDQ57	C (LVDS)*
P19	PR42A	3	RLM0_GPLLT_FB_A	T (LVDS)*	PR57A	3	RLM0_GPLLT_FB_A/RDQS57****	T (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
-	-	-			VCCIO3	3		
P18	PR41B	3	RDQ38	C	PR51B	3	RDQ48	C
N16	PR41A	3	RDQ38	T	PR51A	3	RDQ48	T
GNDIO	GNDIO3	-			GNDIO3	-		
N22	PR40B	3	RDQ38	C (LVDS)*	PR50B	3	RDQ48	C (LVDS)*
N21	PR40A	3	RDQ38	T (LVDS)*	PR50A	3	RDQ48	T (LVDS)*
N17	PR39B	3	RDQ38	C	PR49B	3	RDQ48	C
N18	PR39A	3	RDQ38	T	PR49A	3	RDQ48	T
VCCIO	VCCIO3	3			VCCIO3	3		
M22	PR38B	3	RDQ38	C (LVDS)*	PR48B	3	RDQ48	C (LVDS)*
M21	PR38A	3	RDQS38	T (LVDS)*	PR48A	3	RDQS48	T (LVDS)*
M16	PR37B	3	RDQ38	C	PR47B	3	RDQ48	C
GNDIO	GNDIO3	-			GNDIO3	-		
M17	PR37A	3	RDQ38	T	PR47A	3	RDQ48	T
M20	PR36B	3	RDQ38	C (LVDS)*	PR46B	3	RDQ48	C (LVDS)*
M19	PR36A	3	RDQ38	T (LVDS)*	PR46A	3	RDQ48	T (LVDS)*
M18	PR35B	3	RDQ38	C	PR45B	3	RDQ48	C
VCCIO	VCCIO3	3			VCCIO3	3		
L16	PR35A	3	RDQ38	T	PR45A	3	RDQ48	T
L22	PR34B	3	RDQ38	C (LVDS)*	PR44B	3	RDQ48	C (LVDS)*
L21	PR34A	3	RDQ38	T (LVDS)*	PR44A	3	RDQ48	T (LVDS)*
K22	PR32B	3	RLM1_SPLLC_FB_A	C	PR42B	3	RLM2_SPLLC_FB_A	C
VCCIO	VCCIO3	3			VCCIO3	3		
K21	PR32A	3	RLM1_SPLLT_FB_A	T	PR42A	3	RLM2_SPLLT_FB_A	T
L17	PR31B	3	RLM1_SPLLC_IN_A	C (LVDS)*	PR41B	3	RLM2_SPLLC_IN_A	C (LVDS)*

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
F15	NC	-			NC	-		
F14	NC	-			NC	-		
F13	NC	-			NC	-		
G12	NC	-			NC	-		
G13	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated sysCONFIG pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U12	PB59B	4	BDQ60	C
GNDIO	GNDIO4	-		
AA12	PB60A	4	BDQS60	T
Y12	PB60B	4	BDQ60	C
V12	PB61A	4	BDQ60	T
W12	PB61B	4	BDQ60	C
AB12	PB62A	4	BDQ60	T
AA13	PB62B	4	BDQ60	C
VCCIO	VCCIO4	4		
T12	PB63A	4	BDQ60	T
U13	PB63B	4	BDQ60	C
V13	PB64A	4	BDQ60	T
T13	PB64B	4	BDQ60	C
GNDIO	GNDIO4	-		
AB13	PB65A	4	BDQ69	T
AB14	PB65B	4	BDQ69	C
U14	PB66A	4	BDQ69	T
T14	PB66B	4	BDQ69	C
AA14	PB67A	4	BDQ69	T
VCCIO	VCCIO4	4		
Y14	PB67B	4	BDQ69	C
W14	PB68A	4	BDQ69	T
V14	PB68B	4	BDQ69	C
AB15	PB69A	4	BDQS69	T
GNDIO	GNDIO4	-		
AA15	PB69B	4	BDQ69	C
V15	PB70A	4	BDQ69	T
U15	PB70B	4	BDQ69	C
AB16	PB71A	4	BDQ69	T
VCCIO	VCCIO4	4		
AA16	PB71B	4	BDQ69	C
AB17	PB72A	4	BDQ69	T
AA17	PB72B	4	BDQ69	C
GNDIO	GNDIO4	-		
W20	CFG2	8		
V20	CFG1	8		
V19	CFG0	8		
V22	PROGRAMN	8		
W22	CCLK	8		
U18	INITN	8		
U22	DONE	8		
GNDIO	GNDIO8	-		
U20	WRITEN***	8		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
J11	VCC	-		
J12	VCC	-		
J13	VCC	-		
K14	VCC	-		
K9	VCC	-		
L14	VCC	-		
L9	VCC	-		
M14	VCC	-		
M9	VCC	-		
N14	VCC	-		
N9	VCC	-		
P10	VCC	-		
P11	VCC	-		
P12	VCC	-		
P13	VCC	-		
B5	VCCIO0	0		
B9	VCCIO0	0		
E7	VCCIO0	0		
H9	VCCIO0	0		
D13	VCCIO1	1		
E16	VCCIO1	1		
H14	VCCIO1	1		
E21	VCCIO2	2		
G18	VCCIO2	2		
J15	VCCIO2	2		
K19	VCCIO2	2		
N19	VCCIO3	3		
P15	VCCIO3	3		
T18	VCCIO3	3		
V21	VCCIO3	3		
AA18	VCCIO4	4		
R14	VCCIO4	4		
V16	VCCIO4	4		
W13	VCCIO4	4		
AA5	VCCIO5	5		
R9	VCCIO5	5		
V7	VCCIO5	5		
W10	VCCIO5	5		
N4	VCCIO6	6		
P8	VCCIO6	6		
T5	VCCIO6	6		
V2	VCCIO6	6		
E2	VCCIO7	7		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
K19	VCCIO1	1		
F28	VCCIO2	2		
J25	VCCIO2	2		
K28	VCCIO2	2		
M21	VCCIO2	2		
M24	VCCIO2	2		
N21	VCCIO2	2		
N28	VCCIO2	2		
P21	VCCIO2	2		
R25	VCCIO2	2		
AA28	VCCIO3	3		
AB25	VCCIO3	3		
AE28	VCCIO3	3		
T25	VCCIO3	3		
U21	VCCIO3	3		
V21	VCCIO3	3		
V28	VCCIO3	3		
W21	VCCIO3	3		
W24	VCCIO3	3		
AA18	VCCIO4	4		
AA19	VCCIO4	4		
AE19	VCCIO4	4		
AF22	VCCIO4	4		
AG17	VCCIO4	4		
AG25	VCCIO4	4		
AA12	VCCIO5	5		
AA13	VCCIO5	5		
AE12	VCCIO5	5		
AF9	VCCIO5	5		
AG14	VCCIO5	5		
AG6	VCCIO5	5		
AA3	VCCIO6	6		
AB6	VCCIO6	6		
AE3	VCCIO6	6		
T6	VCCIO6	6		
U10	VCCIO6	6		
V10	VCCIO6	6		
V3	VCCIO6	6		
W10	VCCIO6	6		
W7	VCCIO6	6		
F3	VCCIO7	7		
J6	VCCIO7	7		
K3	VCCIO7	7		

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.